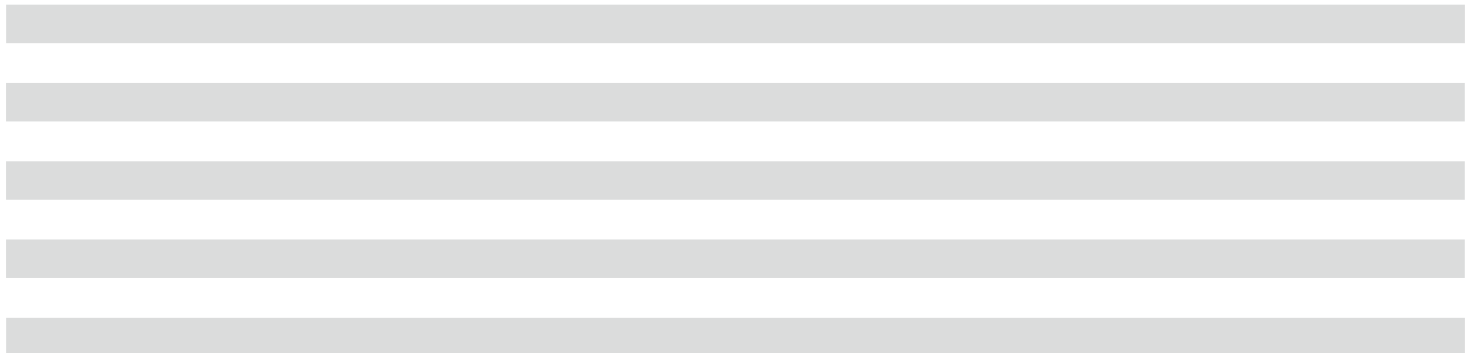


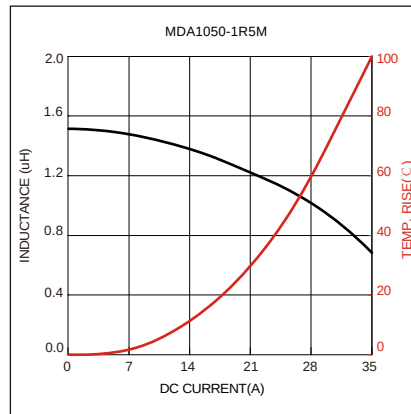
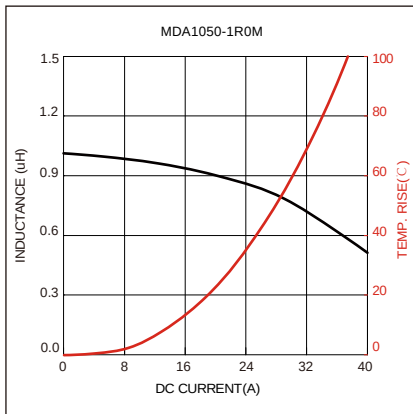
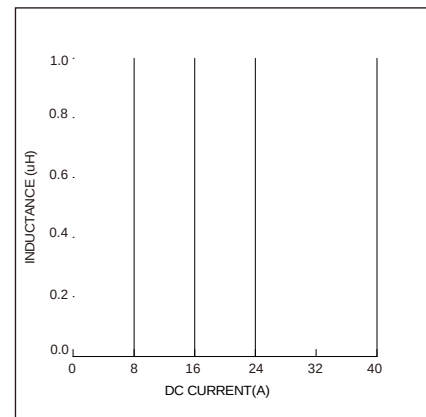
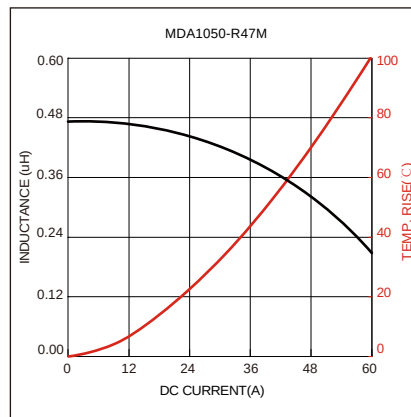
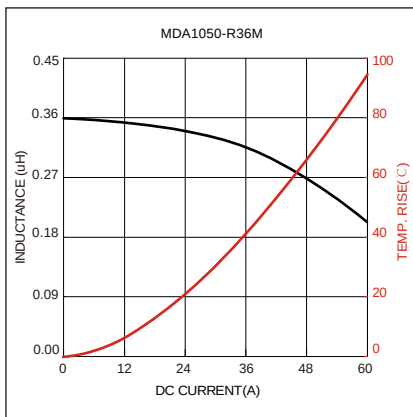
MDA Series

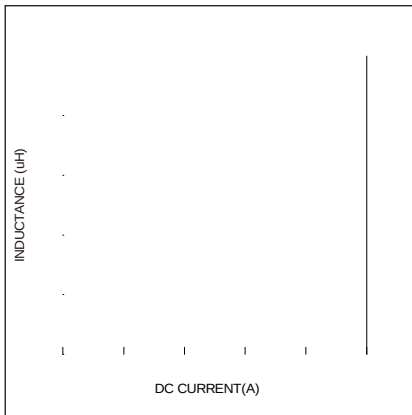
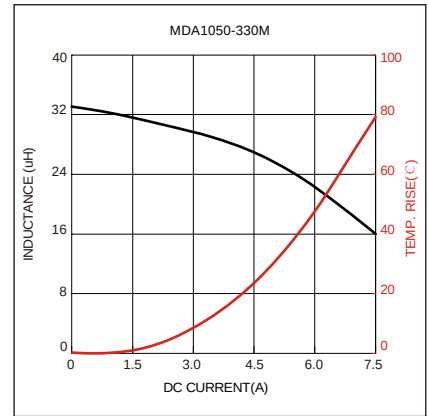
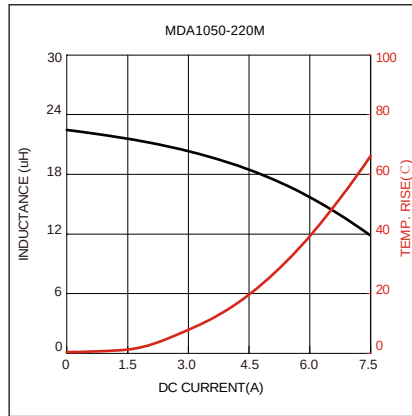
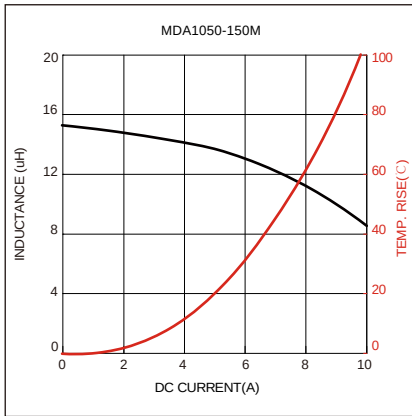
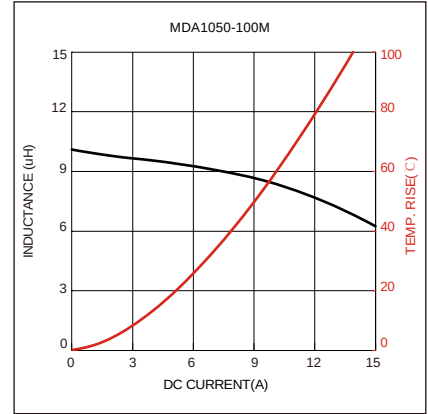
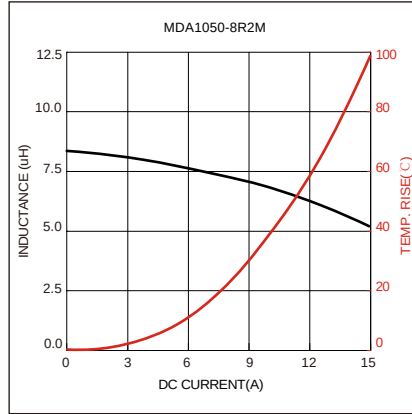
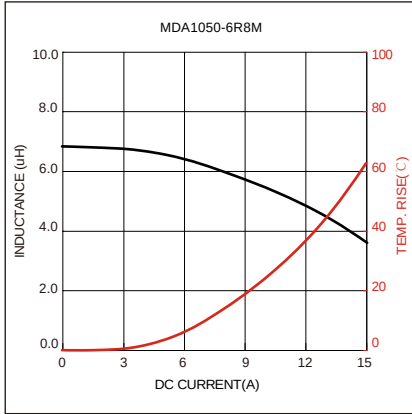
SMD Low Profile High Current Molded Inductor
Size 1050



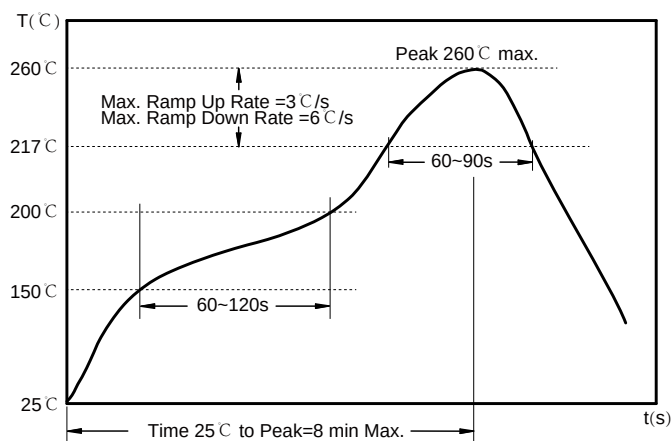
Part No	Inductance @ 100KHz/1V	Tolerance	Temperature Rise Current Typ. (A)	Current Typ. (A)	DC Resistance Typ.	DC Resistance Max.	E
MDA1050-330M	33.0	±20%	5.5	5.8	74.0	86.0	3.0±0.3
MDA1050-470M	47.0	±20%	4.5	4.0	106	127	3.0±0.3

Typical Electrical Characteristics:





Soldering Reflow:



Preheat condition: 150 ~200℃ / 60~120 sec.
Allowed time above 217℃ : 60~90 sec.
Max temperature: 260℃ .
Max time at max temperature: 10 sec.
Allowed Reflow time: 2x max.

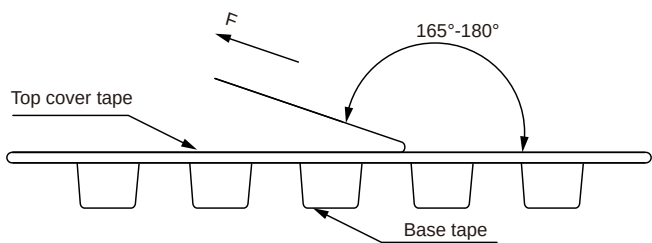
Packaging Information:

Tape Dimension :

Series	A0 (mm)	B0 (mm)
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MDA1050 10.4 ± 0.1

Peel force of top cover tape:

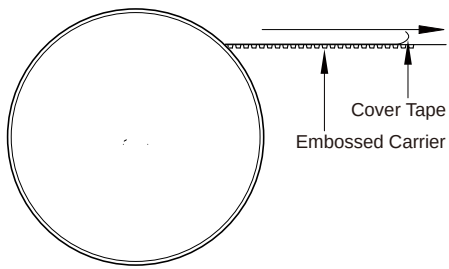


The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

Marking	KH+Printing Inductance+period)
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Reel Dimension: [mm]



Packaging Quantity: